



SANMINA-SCI®

## PCB Fabrication

Kuching, Malaysia



FACILITY FOCUS

High-volume manufacturing for highly complex printed circuit boards (PCBs).

*Leading technologies and processes in a lower-cost geography.*

The Sanmina-SCI® Kuching, Malaysia, facility is a strong option for manufacturing your high-technology printed circuit boards (PCBs). Our Kuching plant specializes in high-volume manufacturing of medium- to high-technology PCBs, offering maximum thickness capabilities of 0.280" and layer counts as high as 30. Whether you need heavy copper inner layers, controlled and differential impedance, Buried Capacitance® or back panels, our Kuching facility can provide the technology you need in the volumes you demand – and at a price you can afford.

### Manufacturing Capabilities

- 12:1 aspect ratios
- Controlled impedance
- Differential impedance
- Depth-controlled drilling
- Laser drilling
- 2 to 30 layers
- Smart drill

### Engineering Capabilities

- Design for Manufacturing (DFM)
- Front-end tooling
- Net-list comparison

### Testing Capabilities

- Universal/dedicated test fixtures
- Surface insulation resistance
- Liquid/liquid temperature cycling
- Flying probe, AOI, IST
- Inductance testing

### Technologies

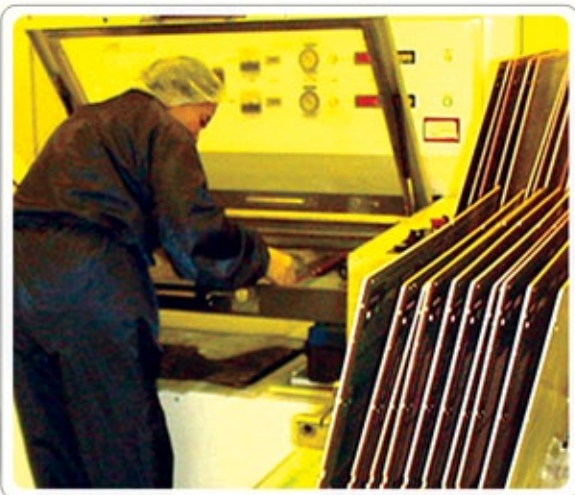
- Lead free, HASL, OSP
- Buried Capacitance®
- Immersion tin, silver
- Electroless nickel
- Immersion gold

### Logistics Services

- Direct order fulfillment
- Consignment and warehousing
- Technical support staff in Asia
- Global technical and customer service

### Certifications

- UL
- ISO 9002
- ISO 9000
- Bellcore compliant



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